

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

Original claims 1-12 (cancelled)

Claim 13 (new): A carrier for supporting and engaging semiconductor products during separating of the products using laser light, wherein the carrier comprises a plate provided with a pattern of holes arranged in a flat carrying side of the plate, and that the plate is manufactured from a material at least substantially not absorbing the laser light.

Claim 14 (new): The carrier as claimed in claim 13, wherein the plate is manufactured from glass or ceramic.

Claim 15 (new): The carrier as claimed in claim 13, wherein the cross-section through the holes close to the carrying side of the plate is larger than at a distance from the carrying side.

Claim 16 (new): The carrier as claimed in claim 15, wherein the holes have a top angle between 15° and 45°, preferably a top angle of 30°.

Claim 17 (new): The carrier as claimed in claim 13, wherein the pattern of holes is grid-shaped and the pitch between the holes is greater than 200 μm .

Claim 18 (new): A holder for supporting and engaging semiconductor products during separating of the products using laser light, comprising a carrier as claimed in claim 13, and means for generating underpressure connecting onto the side of the plate remote from the carrying side.

Claim 19 (new): The holder as claimed in claim 18, wherein the means for generating underpressure connecting onto the side of the plate remote from the carrying side are formed by a chamber connecting onto the carrier and an extractor connecting onto the chamber.

Claim 20 (new): The holder as claimed in claim 18, wherein the chamber is also provided with positioning means for the carrier.

Claim 21 (new): A laser cutting device for supporting and engaging semiconductor products during separating of the products using laser light, provided with a holder as claimed in claim 18, wherein the laser source is located on the carrying side of the plate.

Claim 22 (new): A method for supporting and engaging semiconductor products during separating of the products using laser light, comprising the processing steps of:

- A) placing an assembly of semiconductor products for separating onto a flat plate provided with a pattern of holes,
- B) applying an underpressure to the holes of the pattern of holes such that the assembly of semiconductor products is drawn against the plate,
- C) directing at least one laser beam onto the assembly and cutting through the assembly where this is desired by means of mutual displacement of the laser source and the flat plate such that each severed semiconductor product is still connected to at least one hole in the flat plate, and
- D) taking the separated products from the plate.

Claim 23 (new): The method as claimed in claim 22, wherein the underpressure on the holes is at least partly relieved before the separated products are removed from the plate.

Claim 24 (new): The method as claimed in claim 22, wherein the assembly of semiconductor products is drawn against the plate during processing step B) such that possible deviations in the flatness in the contact side of the assembly are removed by the suction of the plate.